

European Technology Platform

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Elements of Presentation

What are Technology Platforms?

European Commission Involvement

Examples of Experience to Date

Next Steps

Technology Platforms: Concept

Stakeholders getting together to define a Strategic Research Agenda on a number of strategically important issues with high societal relevance where achieving Europe's future growth, competitiveness and sustainable objectives is dependent upon major research and technological advances in the medium to long term.

Technology Platforms: Three Stages

- Stage 1:** Stakeholders get together
- Stage 2:** Stakeholders define the strategic research agenda
- Stage 3:** Stakeholders implement the strategic research agenda

Technology Platforms: Factors for Success

- Flexibility: No “One Size Fits All”**
- Transparency: Clear Rules of Participation**
- Openness to Wide Stakeholder Involvement**
- Operational Focus from Early Stage**
- Committed Involvement of National Authorities**
- Consider Financial Aspects at Outset**

Technology Platforms: European Commission Involvement

NOT:

- Steering / Directing
- Formally Labelling
- “Institutionalising”
- Bound by Views of Platforms

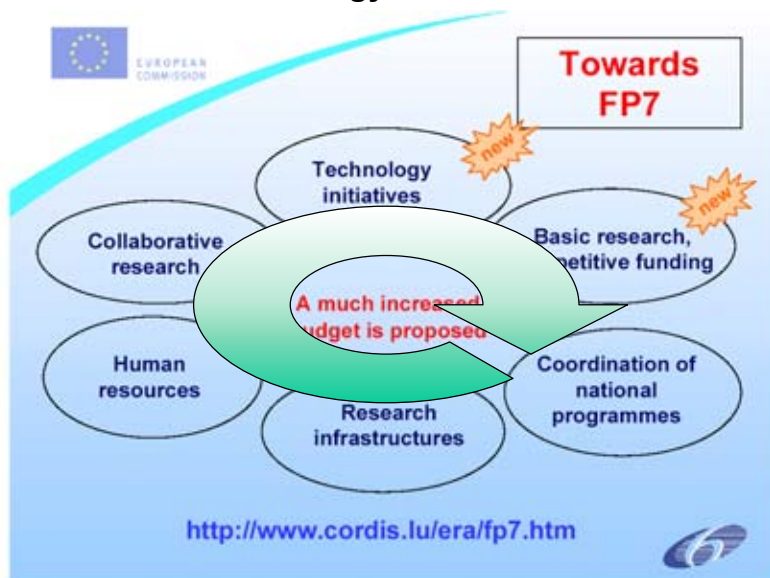
BUT:

- ✓ Fostering a “bottom-up” approach
- ✓ Facilitating
- ✓ Guiding where necessary

Emerging Topics for Platforms

- **Radical Change in a Sector**
Examples: Hydrogen/Fuel Cells, Nanotechnologies
- **Sustainable Development**
Example: Plant Genomics and Biotechnology
- **Public Goods and Services**
Example: Innovative Medicines for Europe
- **Strategic, High-Technology**
Examples: Aeronautics,
Embedded Systems, Nanoelektronik

European Technology Platforms



Existing European Technology Platform Initiatives in the field of Electronics

- **ENIAC** - Nano Electronic Platform Initiative
- **ARTEMIS** – Embedded System Platform
- **Mobile Communication** Technology Platform
- **Smart System Integration** Technology Platform
- **Photonic** Technology Platform



EUROPEAN
COMMISSION
COMMISSION STAFF

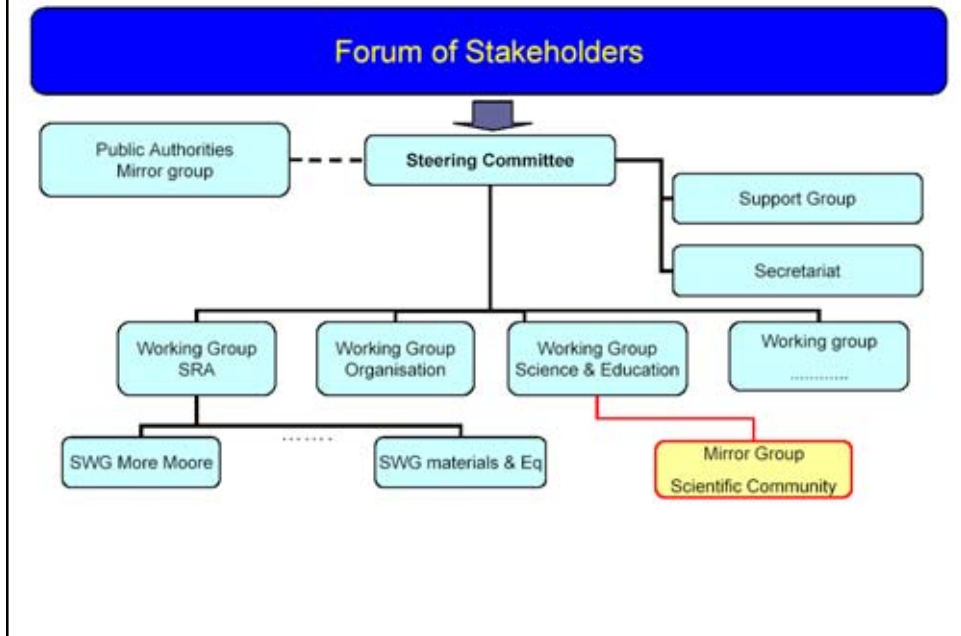
European Technology Platform Nanoelectronics

VISION 2020
NANOELECTRONICS
AT THE CENTRE OF CHANGE

A far-sighted strategy
for Europe

Securing global leadership;
Creating competitive products;
Sustaining high levels of innovation; and
Maintaining top-class skills

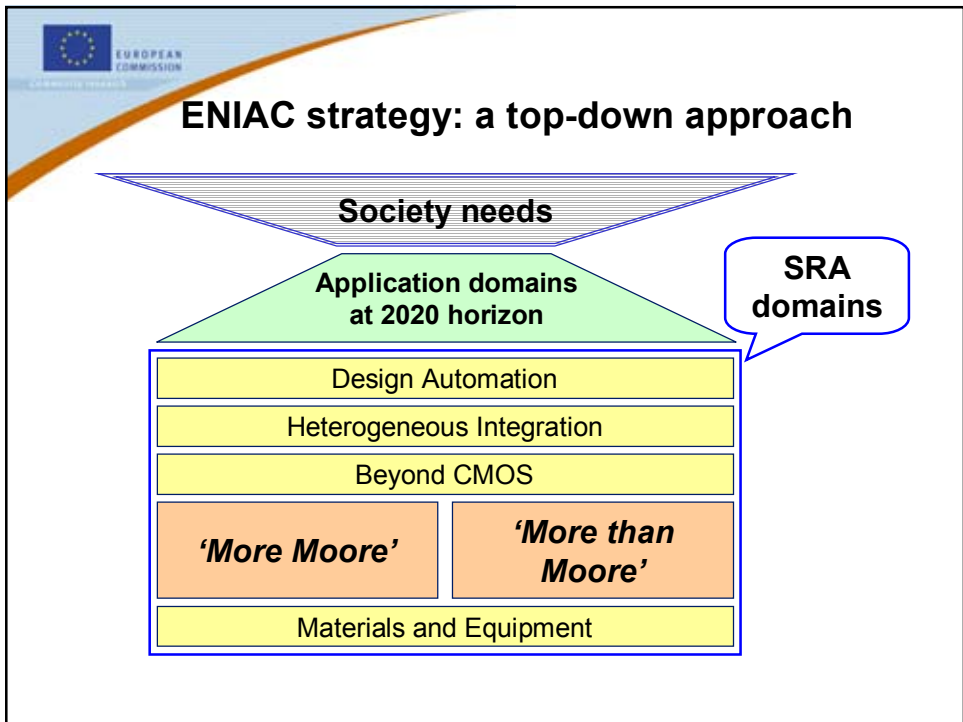
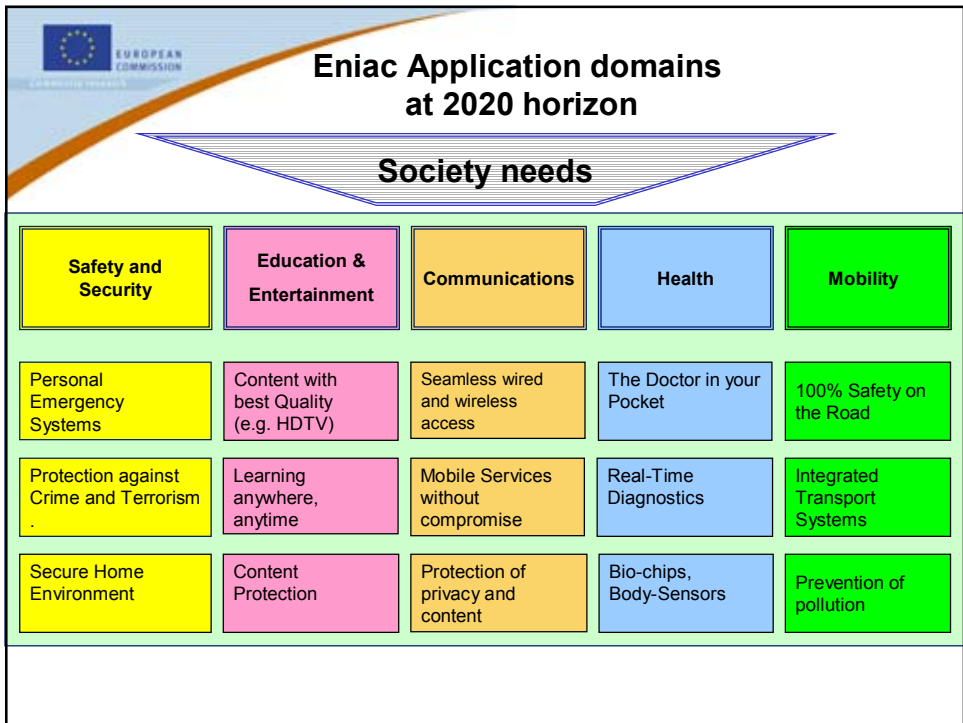
ENIAC Structure



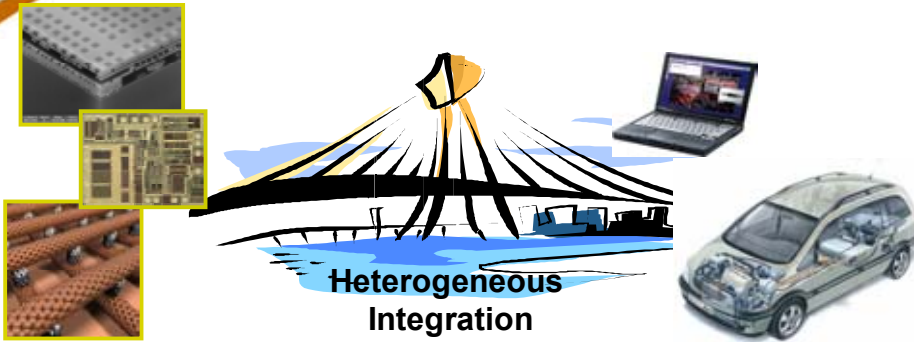

European Technology Platform “Nanoelectronics” High Level Group

HIGH-LEVEL GROUP

 Matti Aaltonen Nokia	 Gilbert Greiner IMEC	 Gilbert Deckert IMEC	 Scott McGeorge Philips Semiconductors	 Krishna Nathan IBM	 Alexander Peitl CNRS
 Hans-Rudolf Dopper AMD	 Doug Dunn ASML Lithography	 Warren East ARM	 Pasquale Polino STMicroelectronics	 Erik Rydberg Thales	 Herbert Reichl Fraunhofer Gesellschaft
 Mikko Eriksson Lithicon	 Derek Gillet Freescale Semiconductor an Motorola Semiconductor Products Sector	 Thomas Hübner CSM	 Ines Thoenes CIA/LETI	 Wolfgang Zierber Infineon Technologies	
 Heiko Kunkert Imath	 Eddy Leppelaere VTT	 Timothy M. Doherty Altilion	 Philippe Stassen European Commission	 Erika Lührmann European Commission	



Heterogeneous Integration Bridging the Gap between Chip and Application



[nm], [μm]

Nanostructures

to

[m]

Application

Heterogeneous Integration is the key for innovations in Europe



European Technology Platform
on
Smart System Integration

Property: **Smart**

- Miniaturised
- Able to communicate
- Networked
- Intelligent Data management
- Self testability
- Fault-tolerant
- Error correcting
- Intelligent E-Management
- Cognitive

Structure: **System**

- Complexity
- Fusion
- Flexibility
- Functionality
- Reliability
- Functional Autonomy
- Decentralisation
- Modularity

Process: **Integration**

- Monolithic Integration
- Packaging
- Hybrid Integration
- Human-Machine-Interface
- Standardisation
- Design for Reliability
- Design for Testing
- Protocols
- Assembly

Technology Aspects

- Combining of optics, mechanics, electronics, fluidics, thermodynamics, chemistry, biology
- Converging technologies: Micro, Nano, Bio, Info, Cogno
- Materials: silicon and non silicon, SiC, alternatives (e.g. polymeres, ceramics, etc.)
- Monolithic, hybrid, multi-chip, WL and other techniques
- Modularisation, characterisation and designability

Thank you